



# CALLING ALL ENGINEERING STUDENTS

Learn more at  
[www.emc2016.emcss.org](http://www.emc2016.emcss.org)

## ANNOUNCING THE 2016 STUDENT EMC HARDWARE DESIGN COMPETITION!

The IEEE EMC Society is pleased to announce the 2016 Student EMC Hardware Design Competition, administered by its Education Committee (previously Education and Student Activities Committee). The objective of the competition is to provide students interested in the field of EMC a hands-on opportunity to apply their knowledge.

This year's focus is on signal integrity. The competitors are required to design a differential-pair circuit producing an optimal signal with minimal distortion. An unpopulated PCB board, board schematic and a few critical components will be provided by the Student Design Competition Chair after reception of the Entry Form.

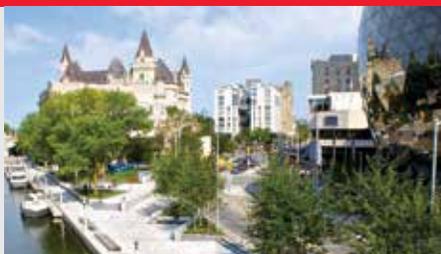
**The winning team will receive a prize of \$900 (USD) and \$2,100 (USD) to cover the cost for one team member to attend the 2016 IEEE International Symposium on EMC held in Ottawa, Canada, July 25-29. The second-place team will receive a prize of \$500 (USD).**

The competition is open to college-level teams both at the undergraduate and graduate level. For more information and to request a parts kit and an entry form, sponsoring faculty members should email the competition administrator, Professor Bogdan Adamczyk at [adamczyk@gvsu.edu](mailto:adamczyk@gvsu.edu).

### CALL FOR STUDENT PAPERS!

The IEEE EMC Society is seeking original, unpublished papers covering all aspects of electromagnetic compatibility, including EMC design, modeling, measurements and education. Graduate and undergraduate authors are eligible for the Best Student Paper contest.

The student must be the primary author and should indicate that they wish to be considered for the contest when submitting the preliminary manuscript. Each student's professor will be asked to certify that the paper is primarily the work of the student. Students submitting EMC and SI/PI Technical Papers must plan to attend.



### COMING JULY, 2016 EXPERIENCE A COLLABORATION OF THE GREATEST MINDS IN ELECTROMAGNETIC COMPATIBILITY AND SIGNAL INTEGRITY ENGINEERING!

- Hear top-rated peer-reviewed technical papers presented by the leading authorities in engineering. These professionals actively participate in the symposium by attending the various sessions and sharing their latest research and expertise.
- Learn from workshops and tutorials presented by representatives of prominent companies and universities in the industry. Presenters hail from companies such as IBM Corp., Intel Corp., Oracle Corp., Cisco Systems, Inc, Samsung Electronics, Ford Motor Co., ETS-Lindgren, NASA, Boeing and many others.
- Observe and interact with live experiments and demonstrations of computational modeling & simulation and hardware that prove important EMC & SI/PI concepts.
- Visit the exhibit floor to explore current technologies, products, services, and more.
- Share fun-filled social events with other students and fellow professionals. This is a chance to meet others and make connections that will last a lifetime and assist in your future career path.

**Deadline for Finished Design Submissions:  
February 29, 2016**

**Attendance is Not Required to Enter the Student  
EMC Hardware Design Competition.**

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